

**LIST OF REFERENCES CITED BY APPLICANT**

(Use Several Sheets if Necessary)

DOCKET NO.: 1298/OF374 SERIAL NO: ~~To Be Assigned~~  
APPLICANT: Sailesh CHITTIPEDDI et al. FILING DATE: Concurrently  
Herewith

09/467,253

**U.S. PATENT DOCUMENTS**

<u>*EXAMINER</u> <u>INITIALS</u>	<u>DOCUMENT</u> <u>NUMBER</u>	<u>DATE</u>	<u>NAME</u>	<u>CLASS</u>	<u>SUBCLASS</u>	<u>FILING DATE</u>
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**FOREIGN PATENT DOCUMENTS**

<u>*EXAMINER</u> <u>INITIALS</u>	<u>DOCUMENT</u> <u>NUMBER</u>	<u>DATE</u>	<u>COUNTRY</u>	<u>CLASS</u>	<u>SUBCLASS</u>	<u>TRANSLATION</u> <u>YES</u> <u>NO</u>
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**OTHER REFERENCES****(INCLUDING AUTHOR, TITLE DATE, PERTINENT PAGES, ETC.)**

\*EXAMINER  
INITIALS

OC Tummala et al., "Microelectronics Packaging Handbook", Section 6.3, pages 366-382, Van Norstrand Reinhold, New York, 1989

EXAMINER: Michelle Estrada DATE CONSIDERED: 6/2/04

\*EXAMINER:

Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.